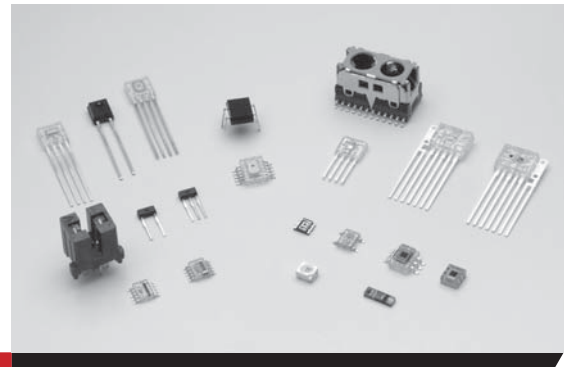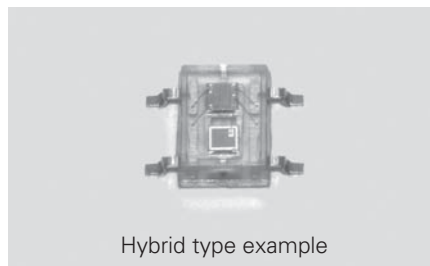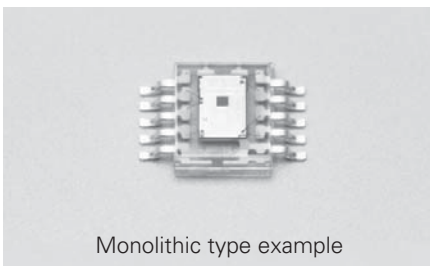# Photo IC

Photo IC

Photo ICs are optical devices that combine a photosensitive section and a signal processing circuit into one package. These devices possess versatile functions according to their particular product applications. Photo ICs offer the following features compared to devices made up of discrete parts on a circuit board.

◆ Compact and lightweight ◆ Resistant to electromagnetic induction noise ◆ High reliability
◆ Ideal for mass production ◆ High cost performance

Photo ICs can be broadly grouped into monolithic types and hybrid types by their structures. The monolithic type contains a photosensor and a signal processing circuit formed on the same chip. This type is extremely resistant to electromagnetic induction noise because there is no wiring between the photosensor and signal processing circuit. In the hybrid type, however, the photosensor and the signal processing IC are formed on separate chips and connected to each other within one package. The hybrid type offers the advantage that specifications such as the photosensor shape and spectral response characteristics are easy to change. When designing a photo IC to custom specifications, it is important to select the photo IC type while seeking a balance between performance and cost.

Hamamatsu offers photo ICs that are optimized for a wide range of applications such as brightness and color sensing, optical links using POF (plastic optical fiber), and synchronous detection for laser printers, etc. Hamamatsu has made intensive R&D efforts over the years to create various types of opto-semiconductor processes and unique IC processes to meet the product specifications needed by our customers. We have established a comprehensive production system ranging from photo IC design to wafer processing, assembly, and inspection processes. We also offer our strong support system for device analysis and evaluation including reliability testing. Feel free to consult with us about photo ICs that match your custom specifications.

Monolithic type example

Hybrid type example

▍Hamamatsu Photo ICs

Application	Product name	Monolithic/hybrid	Output
Illuminance sensor	Photo IC diode	Monolithic	Analog
	Light-to-frequency converter photo IC	Hybrid	Digital
Optical communication (POF)	Transmitter/receiver photo IC for optical link (general-purpose type, for MOST network)	Monolithic or hybrid	Digital
Displacement/rotation sensor	Encoder module	Monolithic	
Color sensor	Digital color sensor, I^{2}C compatible color sensor	Monolithic	
Color, illuminance, and object sensor	Color/proximity sensor	Hybrid	
Optical switch	Light modulation photo IC, photo IC for optical switch	Monolithic	
Print start timing detection in laser printer and the like	Photo IC for laser beam synchronous detection	Hybrid	

1. Illuminance sensors
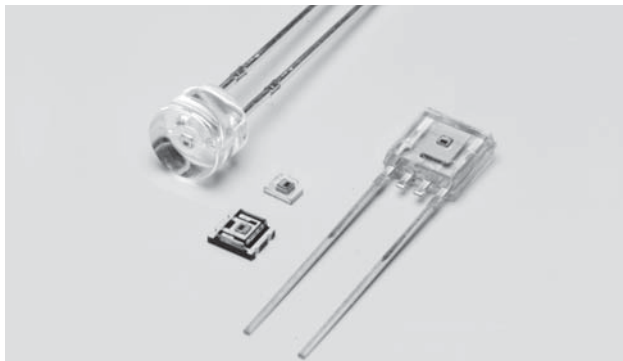
1 - 1　Photo IC diodes

Photo IC diodes are monolithic ICs consisting of a photodiode that generates electrical current from incident light and a circuit section that amplifies the current by several tens of thousands of times. Photo IC diodes provide a current output and can be used in the same way as a photodiode applied with a reverse voltage. Photo IC diodes include visual-sensitive compensation types and infrared types with sensitivity extending to the near infrared range. Packages available include SIP (single inline package), DIP (dual inline package), COB (chip on board), and head-on types. The IC and the package can be customized to match customer needs, ranging from consumer electronics to in-vehicle use.

◻ Features

- Just as easy to use as photodiodes
- Large output equivalent to phototransistors
- Excellent linearity

### ◻ Operating principle and characteristics

Here we describe the operating principle of visual-sensitive compensation type photo IC diodes. The photosensitive area of visual-sensitive compensation types is made up of a photodiode for the main signal and a secondary photodiode for signal compensation. An internal arithmetic circuit subtracts the photocurrent generated in the photodiode for signal compensation from the photocurrent generated in the photodiode for the main signal, in order to obtain spectral response characteristics that block out the infrared range. The signal is then amplified by a current amplifier and is output.

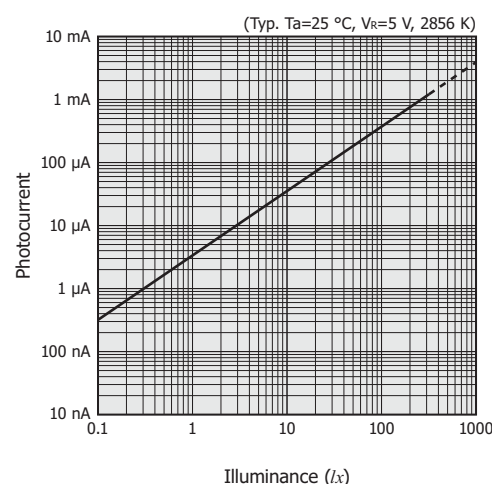[Figure 1-1] Block diagram (visual-sensitive compensation type)

$$fc \approx \frac{1}{2\pi C_L R_L}$$

fc: cutoff frequency
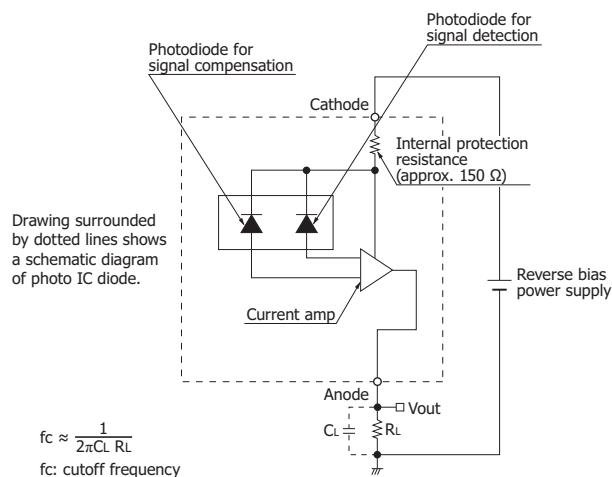
KPICC0163EA

[Figure 1-2] Spectral response
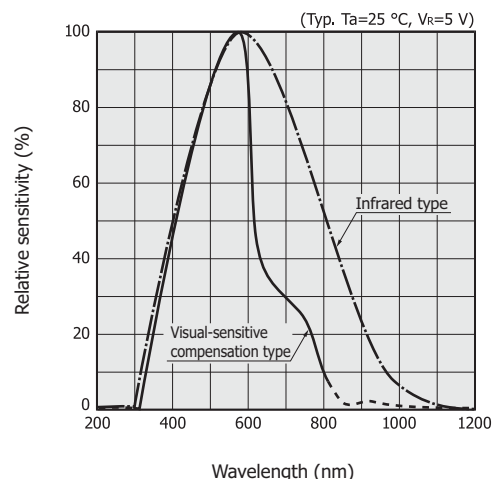
KPICB0084EB

[Figure 1-3] Linearity (visual-sensitive compensation type)

KPICB0083ED

[Table 1-1] Electrical and optical characteristics (visual-sensitive compensation type S9648-200SB)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Spectral response range	λ		-	300 to 820	-	nm
Peak sensitivity wavelength	λp		-	560	-	nm
Dark current	I_D	V_R=5 V	-	1	50	nA
Photocurrent	I_L	V_R=5 V, 2856 K, 100 lx	0.18	-	0.34	mA
Rise time	tr	10 to 90%, V_R=7.5 V R_L=10 kΩ, λ=560 nm	-	6.0	-	ms
Fall time	tf	90 to 10%, V_R=7.5 V R_L=10 kΩ, λ=560 nm	-	2.5	-	ms

How to use

Apply a voltage so that a positive potential is applied to the cathode. If the high-frequency components must be removed, then connect a capacitive load (C_L) as a low-pass filter in parallel with the load resistance (R_L).
The cutoff frequency (fc) is expressed as shown in equation (1).

$$fc \approx \frac{1}{2\pi\ C_L\ R_L} \quad \cdots\cdots\cdots (1)$$

1 - 2　Light-to-frequency converter photo IC
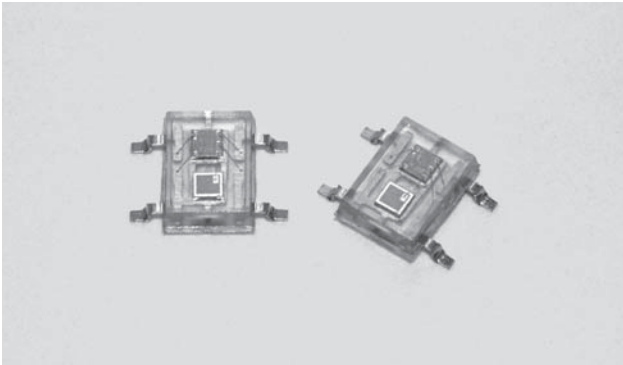
The light-to-frequency converter photo IC is a CMOS photo IC combining a photodiode with a current-to-frequency converter. This photo IC outputs digital pulses supporting CMOS logic, and the output frequency is proportional to the incident light level. This photo IC can be used in various types of light-level sensors.
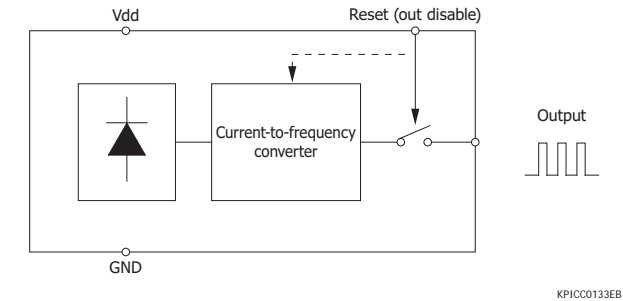
Features

• Wide dynamic range

Ordinary current-to-voltage converter circuits usually have a limited dynamic range due to the noise and supply voltage. This light-to-frequency converter photo IC employs a circuit that converts current directly to a pulse frequency. So the photocurrent of the photodiode is converted to a frequency with no loss in the wide dynamic range. This photo IC therefore achieves a dynamic range of five figures or more.

• Spectral response close to human eye sensitivity

Spectral response characteristics of the photodiode used in the light-to-frequency converter photo IC are close to human eye sensitivity. The IC output nearly matches human eye sensitivity because color temperature errors are minimal.

• High sensitivity

The photodiode in the light-to-frequency converter photo IC is driven under conditions where the bias voltage between the anode and cathode is near zero. This minimizes the dark current and achieves higher sensitivity.

• Digital output

Output is in digital pulses so no troublesome analog processing is required.

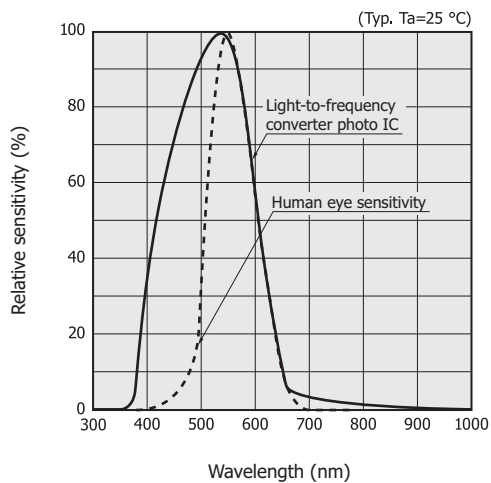## Operating principle and characteristics

The light-to-frequency converter photo IC is made up of a photodiode and current-to-frequency converter. It outputs a pulse frequency proportional to the illuminance. Output is released during the high period of the reset pulse. The output pulse phase is initialized when the reset pulse is changed from high to low.
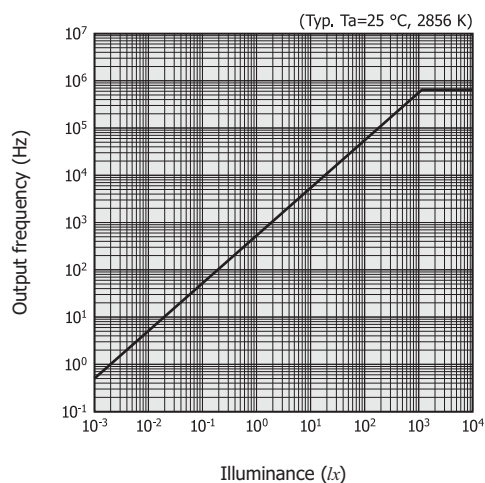
[Figure 1-4] Block diagram

KPICC0133EB

[Figure 1-5] Spectral response

(Typ. Ta=25 °C)

Light-to-frequency converter photo IC

Human eye sensitivity

Relative sensitivity (%)

Wavelength (nm)

KPICB0126EA

[Figure 1-6] Output frequency vs. illuminance

(Typ. Ta=25 °C, 2856 K)

Output frequency (Hz)

Illuminance (lx)

KPICB0091EC

[Figure 1-7] Output waveform example

Illuminance 1 µW

Illuminance 0.1 µW

[Figure 1-8] Connection example

Light-to-frequency converter photo IC

Output

Microcontroller

KPICC0134EB

▣ How to use

To detect illuminance by using the light-to-frequency converter photo IC, find the output frequency by counting the number of pulses in a specified period (Tg). The illuminance can also be detected by finding the half-cycle time of the output. This method is effective when detecting low illuminance or, in other words, during output of a low frequency.

2. Transmitter/receiver photo IC for optical link
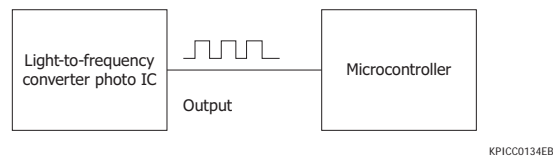
Optical fiber communication using plastic optical fibers (POF) features insusceptibility to external noise, high-speed data communication capability, and the like and is used in in-vehicle, FA, and consumer electronic optical networks. Hamamatsu offers general-purpose types supporting a variety of transmission speeds as well as high-speed, high-reliability types for MOST (Media Oriented Systems Transport) network, which is popular in Europe.

2 - 1 General-purpose type

Transmitter photo IC   Receiver photo IC
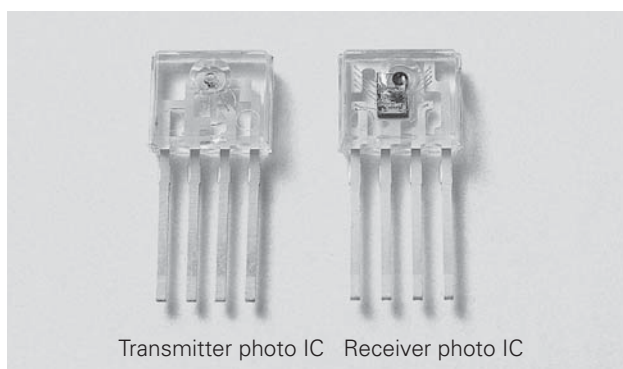
We provide general-purpose optical link receiver photo ICs that support transmission speeds from DC to 100 Mbps.
There are two types of transmitter photo ICs (with built-in LED driver circuit): one type covering DC to 10 Mbps and another covering DC to 100 Mbps. Table 2-1 shows the available receiver photo IC types.

[Table 2-1] General-purpose receiver photo IC for optical link

Type	Supply voltage	Transmission speed	Output level
Low speed, high sensitivity (for long distance communication)	3.3 V ±5%	DC to 1 Mbps	CMOS level
Low speed, ultra low current consumption			
For semi high-speed communication		DC to 10 Mbps	
For high-speed communication		DC to 100 Mbps	

◻ Features

• Monolithic structure (receiver photo IC)

Receiver photo ICs integrate the photodiode and signal processing circuit into a monolithic structure to reduce effects from external electromagnetic noise. Hamamatsu uses a unique PIN bipolar process to form the monolithic structure. This PIN bipolar process allows manufacturing photo ICs with high speed up to 250 Mbps.

• Wide dynamic range

Hamamatsu offers products that cover a wide range of transmission speeds from DC to 100 Mbps. Receiver photo ICs have a wide dynamic range (e.g., the dynamic range of receiver photo ICs for semi high-speed communication: -5 to -30 dBm).

◻ Structure

Figure 2-1 shows a block diagram of the transmitter photo IC. When an signal is input, the LED emits light. The rise time of the optical output waveform is adjusted through resistance and capacitance.
Figure 2-2 shows a block diagram of the receiver photo IC. When an optical signal is input to the photodiode, an amplifier converts the current into voltage and amplifies the signal. Then, a comparator converts the signal into CMOS digital output.

[Figure 2-1] Block diagram (transmitter photo IC)

KPICC0200EB
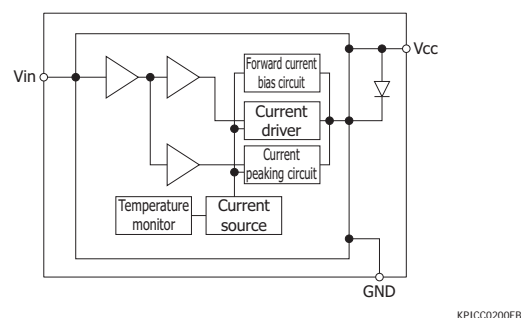
[Figure 2-2] Block diagram (receiver photo IC)

KPICC0201EA
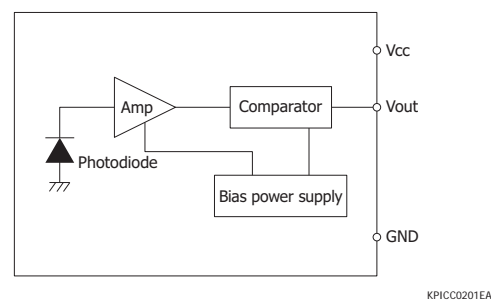
[Figure 2-3] Output waveforms

(a) Optical output waveform of transmitter photo IC (DC to 10 Mbps)
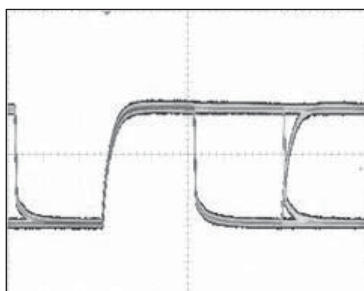
Horizontal axis: 40 ns/div.
PN=2^7-1, 10 Mbps

(b) Digital output waveform of receiver photo IC for semi high-speed communication
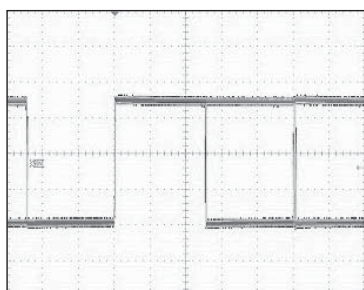
Horizontal axis: 40 ns/div., vertical axis: 1 V/div.
PN=2^7-1, 10 Mbps

2-2 For MOST networks (150 Mbps)

Transmitter photo IC L11354-01   Receiver photo IC S11355-01   Transmitter/receiver photo IC P11379-04AT
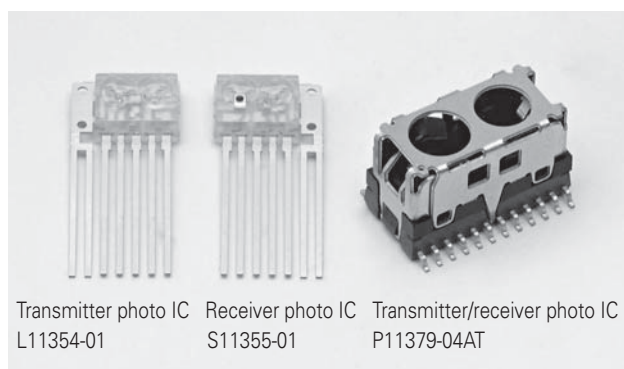
This 150 Mbps optical link photo IC complies with the MOST150 standard. We provide a sidelooker plastic package type and a surface mount type that consists of a transmitter/receiver chip in a single package with an integrated optical fiber connector. The surface mount type features high reliability and supports reflow soldering. We also provide a 25 Mbps data transmission speed type.

□ Features

• Uses high-speed LED (transmitter photo IC)

The transmitter photo IC employs a high-speed, high-power LED with a peak emission wavelength of 650 nm. The driver IC contains an internal temperature-compensation circuit that suppresses optical output fluctuations caused by changes in the ambient temperature.

• Wide dynamic range, standby mode (receiver photo IC)

The receiver photo IC is a hybrid structure integrating a PIN photodiode and CMOS IC, which delivers high-speed operation. It has a wide dynamic range of -2 to -22 dBm and includes a standby function that switches to power-saving mode when no light is input.

• Full differential structure (receiver photo IC)

Receiver photo ICs employ signal processing circuit with a full differential structure that uses a dummy photodiode to reduce effects from power supply noise and external electromagnetic noise. The reduction of noise effects achieves high S/N.

□ Structure

Figure 2-4 shows a block diagram of the transmitter photo IC. When a given electrical signal is input to the input terminal, the RC (resonant cavity) type LED emits light. A temperature monitor circuit senses the ambient temperature and adjusts the LED drive current.
Figure 2-5 shows a block diagram of the receiver photo IC. When the light level exceeding a preset level enters the photodiode, operation shifts from standby mode to operation mode, then the amplifier and LVDS output circuit start operating to output an LVDS signal.

[Figure 2-4] Block diagram (transmitter photo IC)

KPICC0177EA
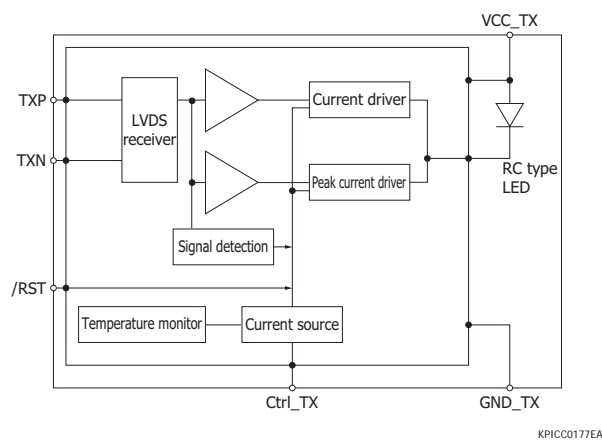
[Figure 2-5] Block diagram (receiver photo IC)
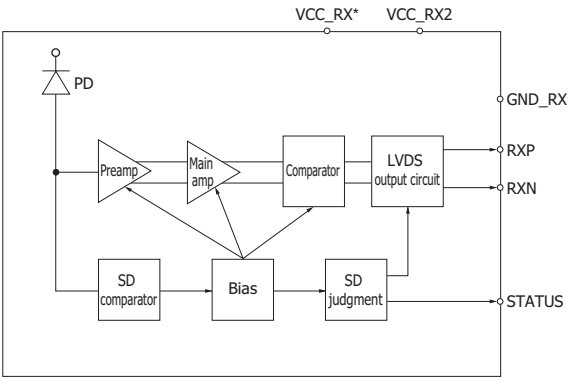
* P11379-04AT only

KPICC0178EB

◻ Characteristics

[Figure 2-6] Output waveforms (eye pattern)

(a) Optical output waveform of transmitter photo IC

MOST stream data, 300 Mbps

(b) Digital output waveform of receiver photo IC
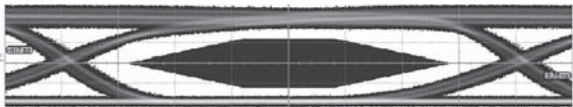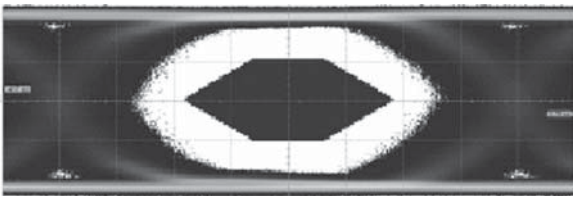

MOST stream data, 300 Mbps, Pin=-21.5 dBm

[Figure 2-7] Connection example
            (transmitter photo IC: L11354-01)
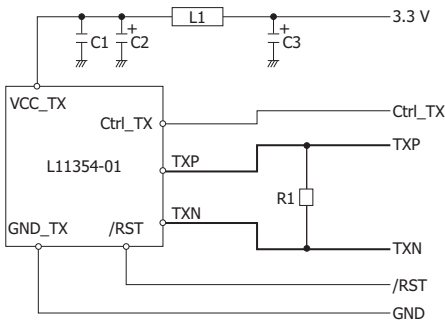
Thick lines: 50 Ω impedance matching

KPICC0179EB

Symbol	Part	Constant	Remarks
R1	Resistor	100 Ω	Terminator for LVDS
L1	Inductance	0.1 μH	For a filter
C1	Capacitor	0.1 μF	Bypass capacitor for noise suppression
C2	Capacitor	10 μF	For a filter
C3	Capacitor	10 μF	For a filter

[Figure 2-8] Connection example
            (receiver photo IC: S11355-01)
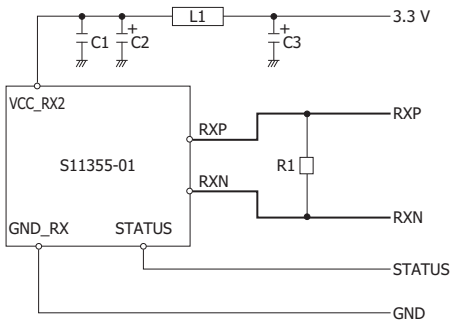
Thick lines: 50 Ω impedance matching

KPICC0180EC

Symbol	Part	Constant	Remarks
R1	Resistor	100 Ω	Terminator for LVDS
L1	Inductance	0.1 μH	For a filter
C1	Capacitor	0.1 μF	Bypass capacitor for noise suppression
C2	Capacitor	10 μF	For a filter
C3	Capacitor	10 μF	For a filter

3. Encoder modules (displacement/rotation sensors)

This is an encoder module that incorporates a red LED and a photo IC designed specifically for optical encoders. This encoder module detects the displacement or rotation angle of the object. When the slit optical pattern attached to the object moves between the LED and photo IC, the 4-element photodiode in the photo IC reads the slit optical pattern, and then outputs the pattern signals (phase A and phase B).

■ Features

• High resolution and high accuracy

Incremental type optical encoders require two LED-photodiode pairs in order to detect the position and direction of movement of the object. Using multiple discrete LED-photodiode pairs has the disadvantage that characteristics vary between components. However, this encoder module incorporates one LED and a single-chip 4-element photodiode, so there are no problems due to variations in characteristics between components. Moreover, element position accuracy is high, so both high resolution and high accuracy are ensured.

• Low current consumption

Hamamatsu encoder module incorporates one red LED and one photo IC which are built into a single module to ensure low current consumption.

• Small size

The encoder module uses a small package with positioning pins.
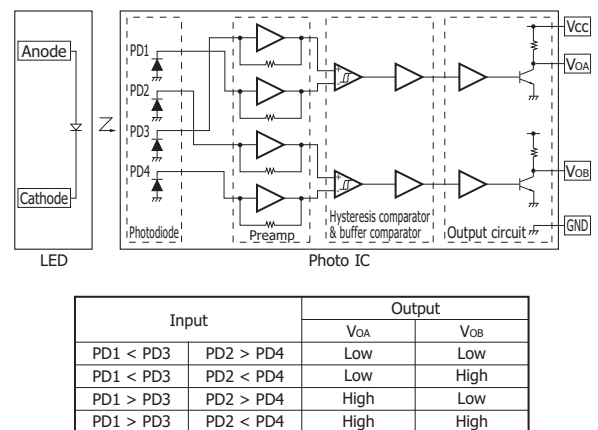
■ Operating principle and how to use

A block diagram of this encoder module is shown in Figure 3-1.
A light spot emitted from the LED is transformed into light/dark patterns via the slits and projected onto the photosensitive area. Figure 3-3 shows recommended slit sizes in the slit plate for this encoder module.

The 4-element photodiode has four photosensitive areas which are PD1, PD2, PD3, and PD4. The photo IC output is a 2-phase digital output (TTL compatible) consisting of phase A and phase B. Phase A (V_{OA}) shows which of PD1 or PD3 is receiving more light, and phase B (V_{OB}) shows which of PD2 or PD4 is receiving more light.
Figure 3-4 shows changes in the signal amount that was input to PD1 to PD4 when there was movement of the light/dark pattern created by the slits, along with results obtained when the electrical current from that input signal was converted into a 2-phase digital signal via the preamp, comparator, and output circuit.

[Figure 3-1] Block diagram and truth table

Input		Output	
		V_{OA}	V_{OB}
PD1 < PD3	PD2 > PD4	Low	Low
PD1 < PD3	PD2 < PD4	Low	High
PD1 > PD3	PD2 > PD4	High	Low
PD1 > PD3	PD2 < PD4	High	High

KPCC0011ED

[Figure 3-2] Dimensional outline (unit: mm)

① V_{OA}
② GND
③ Vcc
④ V_{OB}
⑤ Cathode
⑥ Anode

Tolerance unless otherwise noted: ±0.1, ±2°
Lead position is specified at the reference plane.
Values in parentheses indicate reference values.
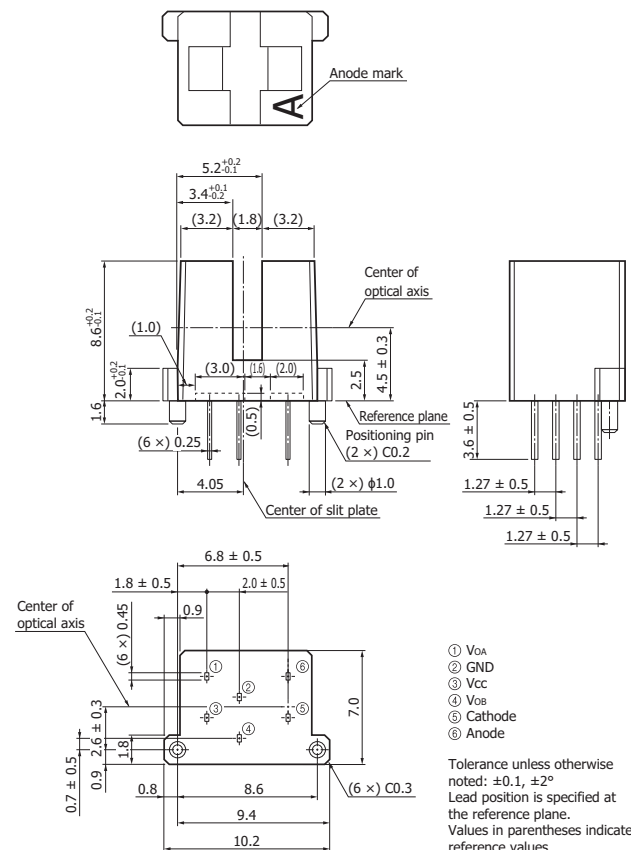
KPCA0010EB

[Figure 3-3] Recommended slit dimensions (unit: mm, t=0.1)
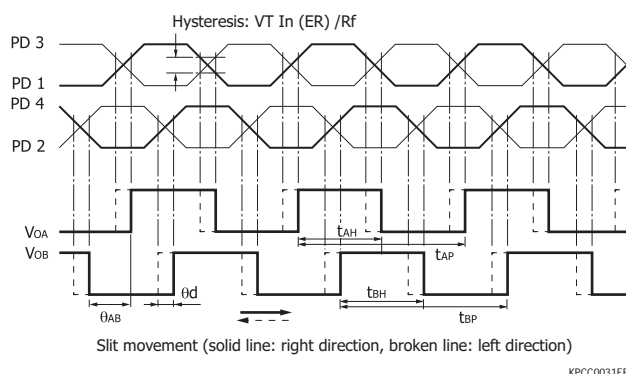(See Figure 3-2 for the center position of slit plate.)
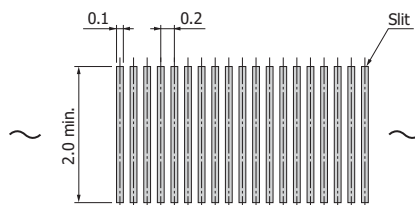
KPCC0013EA

[Figure 3-4] Timing chart

Slit movement (solid line: right direction, broken line: left direction)

KPCC0031EE

The encoder module detects the distance and direction that the slit optical pattern moves, but it cannot detect the absolute position of the slit optical pattern itself. To detect the absolute position of slit optical pattern, the origin point of the slit plate must be specified, and the amount of movement from the origin point is then detected. To do this, a device is needed for calculating the encoder module's output change count from the origin point.

Additions to the output change count are judged as movement farther from the origin point, while subtractions are viewed as movement nearer the origin point. This judgment is made by the 2-phase digital output (V_{OA}, V_{OB}) making either of the following transitions.

(L, L)→(L, H)→(H, H)→(H, L)→(L, L)

(L, L)→(H, L)→(H, H)→(L, H)→(L, L)

[Figure 3-5] Application circuit example
(CW/CCW pulse signal generator circuit)
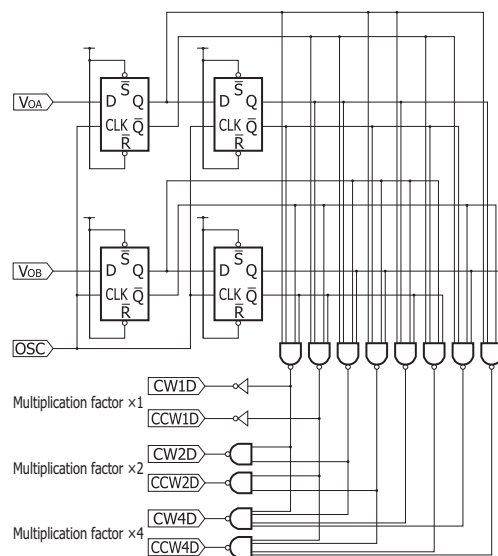
KPICC0032EA

The circuit in Figure 3-5 is a CW (forward direction)/CCW (reverse direction) pulse signal generator circuit that generates up-count signals and down-count signals for counting movement distance and rotation angles. This circuit detects the order of state transitions in V_{OA} and V_{OB} at the OSC signal timing which is used as the sampling signal, and generates pulse signals to the CWnD terminal in response to state transitions in the forward direction and to the CCWnD terminal in response to state transitions in the reverse direction (CWnD/CCWnD are output terminals for the multiplication factor × n). These CWnD/CCWnD terminals generate "n" number of pulses per one state transition period of V_{OA} and V_{OB}. This pulse width is equal to one period of the sampling signal. Figure 3-6 shows pulse signals appearing at the output terminal in response to state transitions of OSC, V_{OA}, and V_{OB}.

A suitable sampling signal frequency is 40 or more times larger than the maximum frequency of one period of the V_{OA} and V_{OB} state transitions (in Figure 3-6 this is 16 times for

[Figure 3-6] Decoder output timing chart (when used with circuit shown in Figure 3-5)
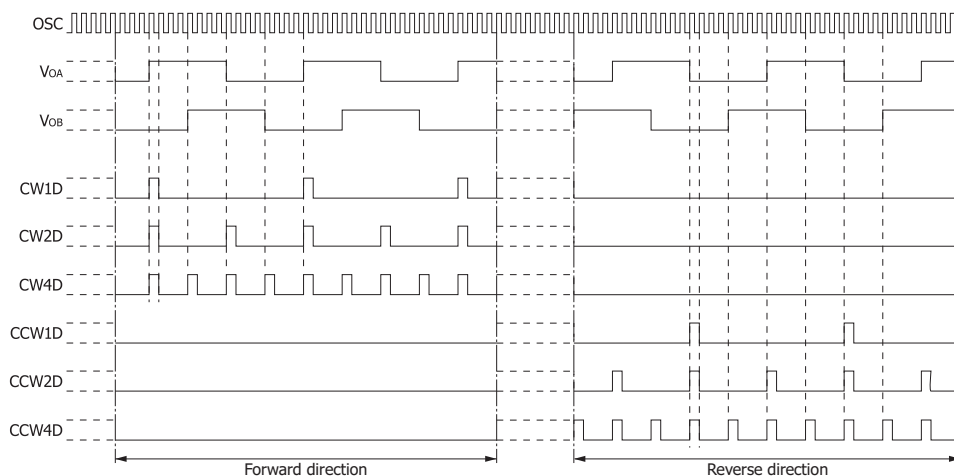
KPICC0034EA

purposes of simplicity). Pulses appearing at each terminal are generated with a slight delay from the instant that the defined state transition occurs [maximum theoretical delay time = 1/{2 × OSC frequency (unit: cycles)}]. Each of these signals is input to the up-count terminal and down-count terminal of the up/down counter. The amount of movement from the origin point can then be detected with a circuit that clears the up/down counter at origin position.

4. Color sensors

4-1 Digital color sensors
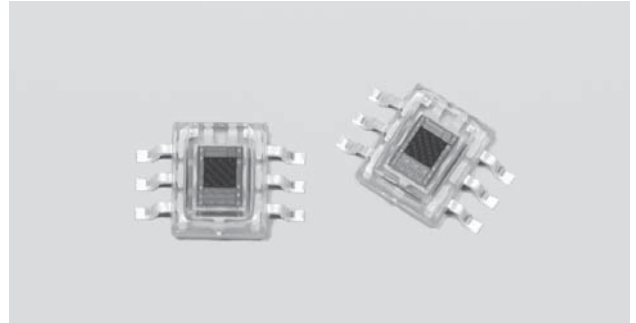
This digital color sensor converts the RGB components of light into 12-bit digital signals for output as serial data. The digital output makes handling the data very simple. One typical application for this digital color sensor is adjusting the backlighting for RGB-LED back-lit liquid crystal displays. To handle deterioration that occurs in LED over time, the digital color sensor monitors the LED brightness and feeds back that information to the LED driver circuit to stabilize the color tint and brightness of the liquid crystal display. This digital color sensor is also widely used to make various color measurements.

■ Features

• 9 × 9 element photodiode

This digital color sensor is a monolithic photo IC that integrates a photodiode and analog/digital circuits. The photodiode consists of 9 × 9 elements arranged in a mosaic pattern. Each element, based on the on-chip filter, is sensitive to one of three colors which are red ($\lambda p=610$ nm), green ($\lambda p=540$ nm), and blue ($\lambda p=465$ nm). The mosaic pattern of the 9 × 9 elements helps reduce effects due to variations in brightness.

• 2-step sensitivity setting

Sensitivity can be selected from 2-step settings (high-sensitivity mode and low-sensitivity mode) to measure light over a wide illuminance range. The photosensitive area varies depending on whether high-sensitivity or low-sensitivity mode is used. (High-sensitivity mode uses 9 × 9 elements, and low-sensitivity mode uses only 3 × 3 elements in the center.)

• 12-bit digital output

The light signal measured by the photodiodes is amplified and converted into a 12-bit digital signal.
Each of the RGB photodiodes arranged in a mosaic pattern has an internal amplifier, so the RGB components of the incident light can be simultaneously measured with high accuracy.

■ Structure and operating principle

The amplifiers in this digital color sensor utilize a light-to-frequency converter. The output from the light-to-frequency converter is a square wave (digital signal), and its frequency is proportional to the incident light level. Outputs from each light-to-frequency converter are counted during the high period of the Gate terminal, and the count value is held in a register. This count value is then serially output from the Dout terminal according to the color in synchronization with pulses that are fed to the CK terminal. The colors are output in the sequence "red" → "green" → "blue," and each color output is 12 bits.

[Figure 4-1] Block diagram

KPICC0110EC
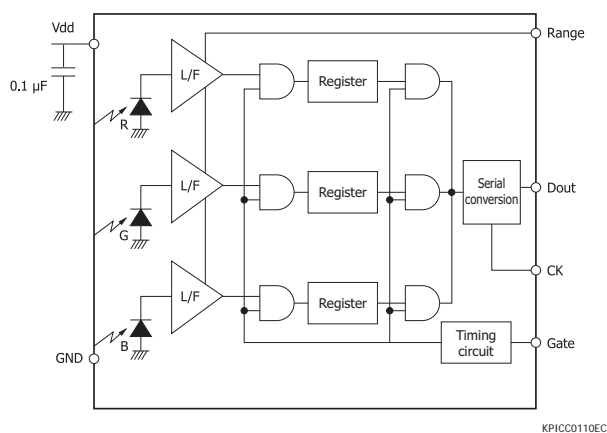
[Figure 4-2] Enlarged view of photosensitive area (unit: μm)

For red
For green
For blue
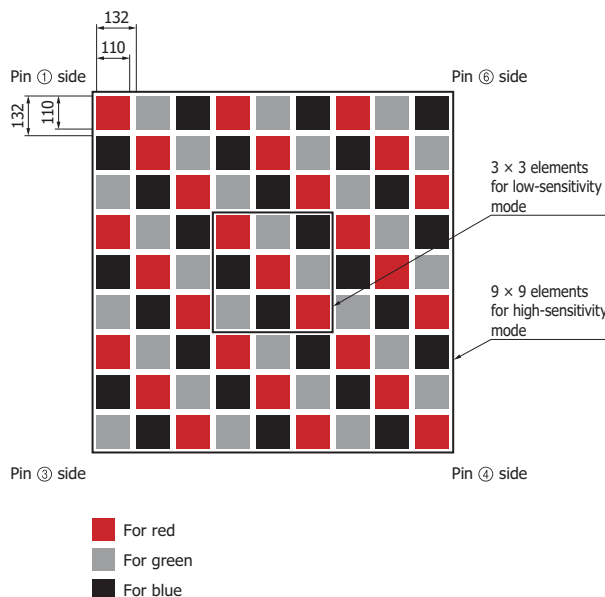
Note: Gaps between elements are light-shielded.

KPICC0124EA

[Table 4-1] Sensitivity setting

Gain	Mode	Effective photosensitive area
High	High sensitivity	9 × 9 elements
Low	Low sensitivity	3 × 3 elements

■ Characteristics

[Figure 4-3] Spectral response
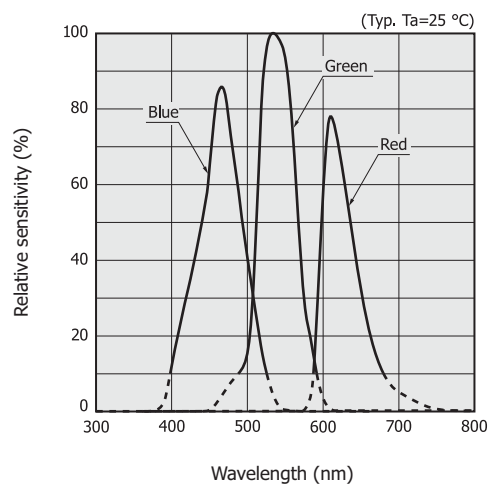
KPICB0089EA

[Figure 4-4] Output vs. illuminance

(a) Low gain

KPICB0099EA

(b) High gain

KPICB0100EA

[Figure 4-5] Timing chart (digital color sensor)

Operating sequence
(1) Set the Gate terminal and CK terminal to low.
(2) Select the desired sensitivity with the Range terminal.
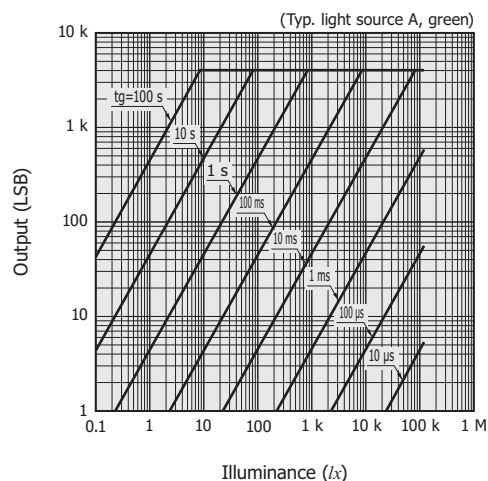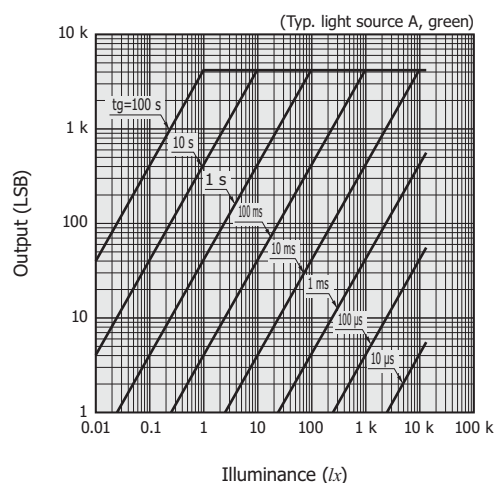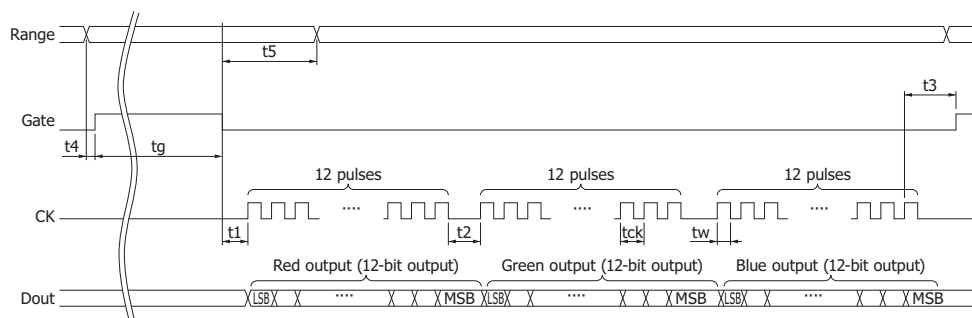(3) Set the Gate terminal from low to high to start integrating the light level.
(4) After the desired integration time (tg) has passed, set the Gate terminal from high to low to end the light level integration.
(5) Measurement data is output from the Dout terminal by inputting 36 CK pulses to the CK terminal.

Note 1: A total of 36 CK pulses are required to read out 3-color measurement data. Red data is output by the first 12 pulses, green data by the next 12 pulses, and blue data by the last 12 pulses. Measurement data is output from the LSB side.
Note 2: Measurement data changes at the CK pulse rising edge.
Note 3: Do not switch the Range terminal during integration time (tg).

KPICC0115EB

■ How to use

The only input signals required by the digital color sensor are a "Range" signal for setting the sensitivity, a "Gate" signal for setting the light integration time, and a "CK" signal for extracting the 12-bit digital data measured from the light [Figure 4-5]. The input and output for digital color sensors are both digital signals and so can be directly connected to the microcontroller and easily used. The only required external component is a bypass capacitor (0.1 µF) that should be inserted between the power supply and the ground.
An infrared cutoff filter is attached to the top surface of the package of the digital color sensor to remove infrared light. However, light from the side of the package does not pass through the infrared cutoff filter. Some countermeasure such as using an aperture is needed to remove infrared light that may enter the sensor without passing through the infrared cutoff filter.

4 - 2 I^{2}C compatible color sensors
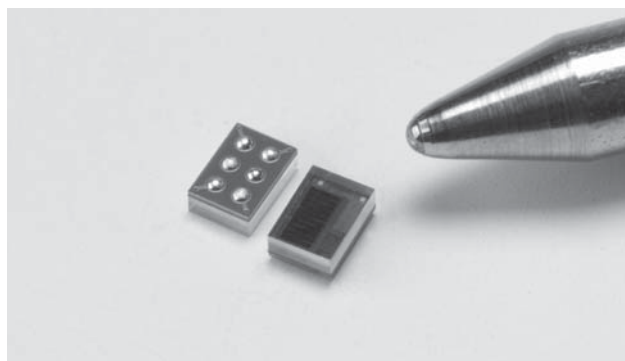
This color sensor incorporates an I^{2}C interface. It is sensitive to red (λp=615 nm), green (λp=530 nm), blue (λp=460 nm), and infrared (λp=855 nm) light, and outputs detected results as 16-bit digital data for each color. Four 16-bit registers are also included to measure RGB and infrared light sequentially. The sensitivity and integration time are adjustable so that light measurements can be performed over a wide dynamic range.
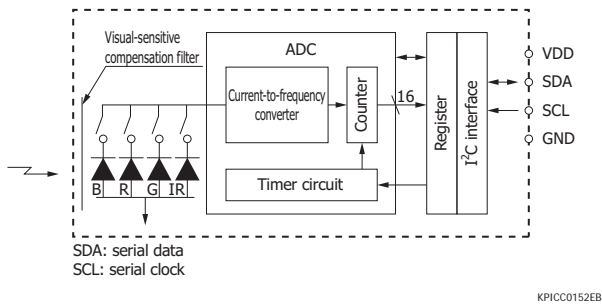
■ Features

• Supports I^{2}C

• Sequential measurements of RGB and infrared light

• 2-step sensitivity switching (sensitivity ratio 1:10)

• Adjustable sensitivity (1 to 65535 times) by setting the integration time

• Low voltage (2.5 V, 3.3 V) operation

• Low current consumption (75 µA typ.)

• Small package (surface mount wafer level package)
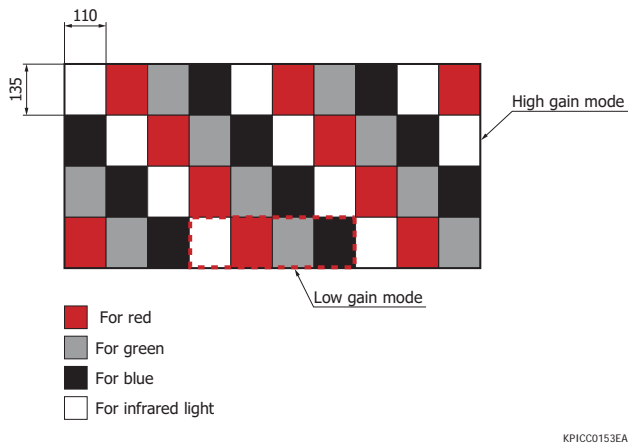
■ Structure and operating principle

This I^{2}C compatible color sensor is made up of a visual-sensitive compensation filter, photodiode, current-to-frequency converter, counter, timer circuit, register, I^{2}C interface, etc. [Figure 4-6] The photodiode consists of 4 × 10 elements arranged in a mosaic pattern [Figure 4-7], and the size of each element is 110 × 135 µm. In ordinary color sensors, strong infrared light such as from remote controls might cause errors in color detection. This I^{2}C compatible color sensor, however, prevents such detection errors using its infrared detection function.
The colors being measured are automatically selected by a switch, so they are sequentially measured in the order of red, green, blue, and infrared. Furthermore, sensitivity and integration time can be specified. The 16-bit data for each color stored in the registers can be read out through the I^{2}C interface.
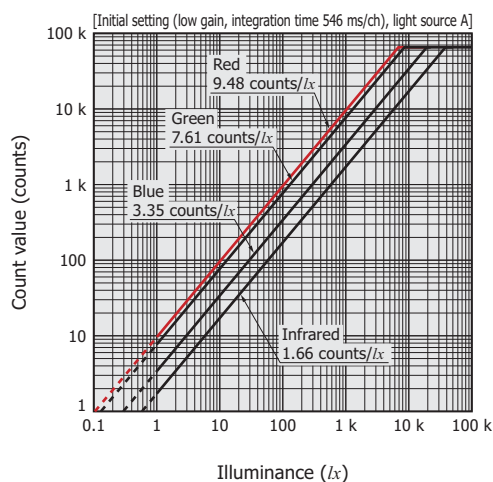
[Figure 4-6] Block diagram

SDA: serial data
SCL: serial clock

KPICC0152EB

[Figure 4-7] Enlarged view of photosensitive area (unit: μm)

High gain mode

Low gain mode

■ For red
■ For green
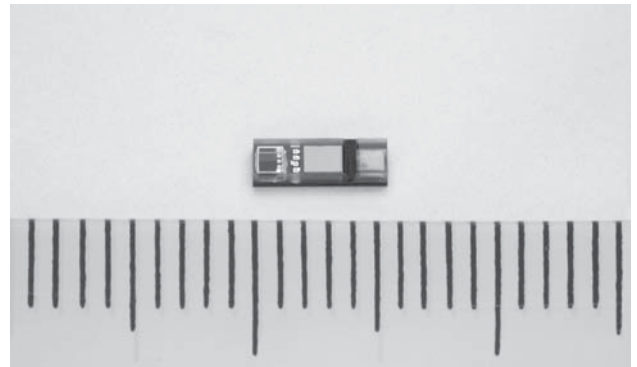■ For blue
□ For infrared light

KPICC0153EA

■ Characteristics

In low gain mode, a single-element photodiode in the bottom center is used to measure each color. In high gain mode, however, a 10-element photodiode is used for each color. The gain switching sensitivity ratio is therefore 1 to 10. Integration time (Tint) is selectable from four preset types (184 μs, 2.88 ms, 46 ms, and 368 ms). If even higher sensitivity is needed, the integration time can be set to a constant multiple [1 to 65535 (16 bits or less)] of these four types of integration times.
The default is set to low-gain mode at an integration time of 546 ms/ch (3120 times 175 μs).

[Figure 4-8] Count value vs. illuminance (typical example)

[Initial setting (low gain, integration time 546 ms/ch), light source A]

Red
9.48 counts/lx

Green
7.61 counts/lx

Blue
3.35 counts/lx

Infrared
1.66 counts/lx

Count value (counts)

Illuminance (lx)

KPICB0130EC

4 - 3 Color/proximity sensors

The color/proximity sensor is a multifunctional sensor that incorporates a color sensor, proximity sensor, and 3-color LED in a small package (5.5 × 1.7 × 1.0 mm). It can be used to adjust the display image quality, perform touchscreen on/off control, indicate incoming calls, and so forth on smartphones and the like. Color sensors not only detect the RGB ratios of ambient light but also function as illuminance sensors. This feature enables image quality to be adjusted in fine detail. In smartphone applications, the proximity sensor detects when a face draws near and turns off the touchscreen function and the LCD backlight. The 3-color LED indicates incoming calls. The red LED also functions as the proximity sensor emitter.

■ Features

• I²C interface 400 kHz, Fast mode

• Low voltage (2.5 V, 3.3 V) operation

• 1.8 V I²C bus voltage compatible

• Low current consumption

• Small package: 5.5 × 1.7 × 1.0 mm

• Supports reflow soldering

• No need to calibrate distance inconsistencies at the time of shipment (30 mm ± 20%)

• Proximity distance, LED driver current, and measurement interval can be specified through the I²C registers.

• Optical synchronous detection with little effect from background light

■ Structure

(1) Color sensor

The color sensor has three channels consisting of R, G, and B. It measures color temperature with high accuracy and high sensitivity (from as low as 1 mlx). It has a built-in 16-bit A/D converter and continuously measures the ratios between the three colors: red (615 nm), green (530

nm), and blue (460 nm). The sensor detects sunlight and room light (fluorescent lamp, incandescent lamp, etc.) and automatically adjusts with high reproducibility the color temperature and brightness of the LCD screen.

The color sensor also functions as an illuminance sensor to adjust the brightness of the LCD screen to a comfortable viewing level. It detects ambient brightness in the wavelength region where the human eye is sensitive and controls the LCD backlight luminance accordingly in order to make the LCD easier to view and also contribute to power savings.
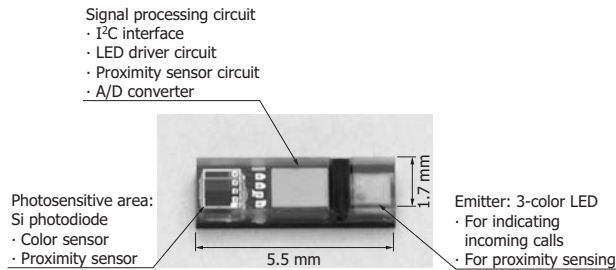
(2) Proximity sensor

The proximity sensor receives the red light from the 3-color LED that is reflected from an object (e.g., face) to detect whether the object is drawing near. For example, in the case of smartphones, the sensor detects the distance between the smartphone and the owner's face and disables the touchscreen control and turns off the LCD backlight during a conversation in order to prevent inadvertent operation and also to save power.
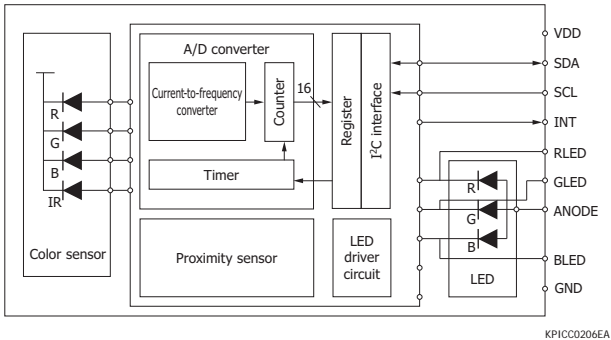
(3) 3-color LED

The 3-color LED mixes the R, G, and B colors to produce full color. Numerous colors can be specified through the I^2C interface. In smartphones, different colors can be assigned to incoming calls, incoming mail, incoming SMS, and so on.

[Figure 4-9] Structure diagram

Signal processing circuit
· I^2C interface
· LED driver circuit
· Proximity sensor circuit
· A/D converter

Photosensitive area:
Si photodiode
· Color sensor
· Proximity sensor

1.7 mm

5.5 mm

Emitter: 3-color LED
· For indicating incoming calls
· For proximity sensing

[Figure 4-10] Block diagram

KPICC0206EA

☐ Characteristics

[Figure 4-11] Spectral response

KPICB0179EA
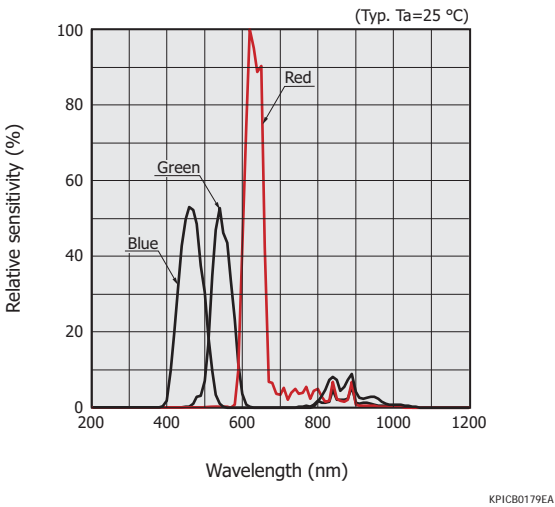
[Figure 4-12] Proximity distance vs. LED current (typical example)

KPICB0180EA

15
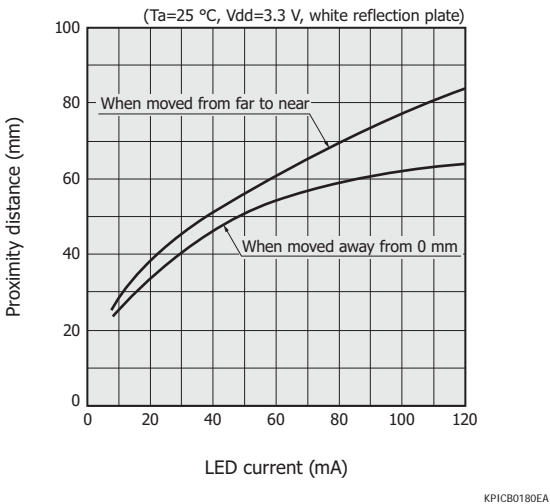
5. Light modulation photo IC (for optical switch)
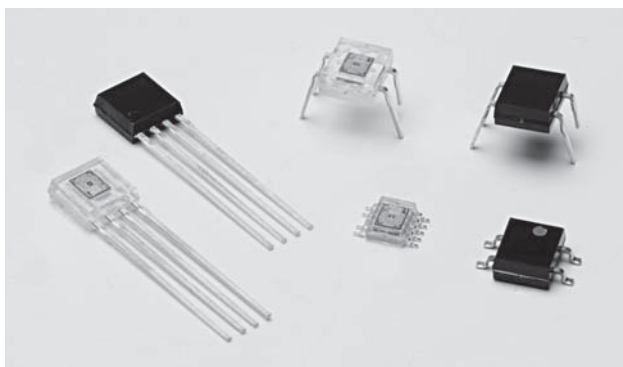
Light modulation photo ICs were developed to optically detect objects. Optical detection of objects usually uses a photosensor/light emitter pair, like a photointerrupter and photoreflector which detect an object when it interrupts or reflects light. However, detection errors might occur if fluctuating background light such as room lighting strikes the photosensor. To prevent these detection errors, one typical method uses optical filters by utilizing the difference in wavelengths between the signal light and background light. However, this method does not work if the background light level is too strong. Light modulation photo ICs deal with this problem by using a synchronous detection method to reduce detection errors and ensure a stable output even if fluctuating background light strikes the photosensor. This synchronous detection method pulse-modulates the signal light and detects it in synchronization with the modulation timing to reduce effects from "noise light" that enters the photosensor asynchronously.

■ Features

• Fewer detection errors even if fluctuating background light hits the photosensor

A typical light modulation photo IC consists of an oscillator, a timing signal generator, an LED driver circuit, a photodiode, a preamp, a comparator, a signal processing circuit, an output circuit, and so on, which are all integrated on a monolithic chip. Connecting an external LED to this photo IC allows optical synchronous detection.

• Various types are available for handling higher background light levels or offering higher sensitivity.

Hamamatsu provides types usable even under higher background light levels (10000 lx typ.), as well as high sensitivity types (lower detection level: 0.2 μW/mm^2 typ.), and asynchronous type that does not require wiring to a light emitter. These are supplied in various packages (DIP, SIP, and surface mount type).
Types for higher background light level (S4282-51, S6986, S10053) have a preamp with special measures added to deal with DC light input. This ensures reliable detection of signal light even under high-illuminance DC background light. On the other hand, high-sensitivity types (S6809, S6846, S7136-10) allow making the detection distance even longer.

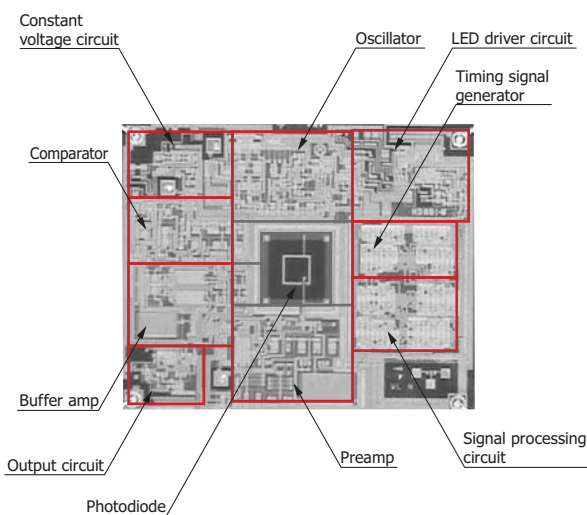## [Figure 5-1] Block diagram and truth table
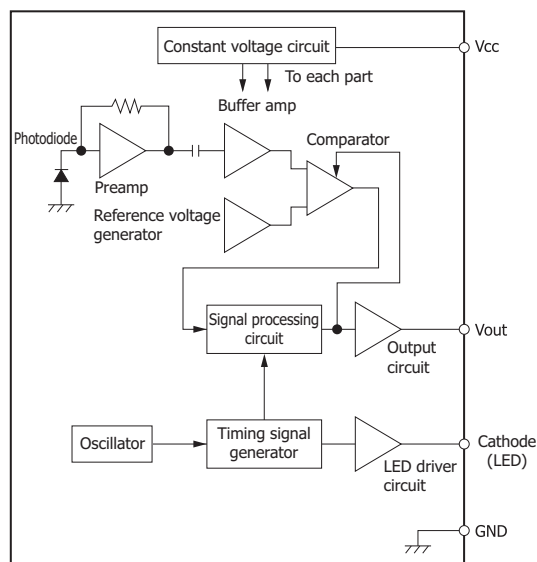
Truth table

Input	Output level
Light on	Low
Light off	High

KPICC0002EB

[Figure 5-2] Enlarged photo of chip and block layout

■ Structure

Circuit block configurations of a light modulation photo IC are described below.

(1) Oscillator and timing signal generator

The oscillator produces a reference oscillation output by charging and discharging the internal capacitor with a constant current. The oscillation output is fed to the timing signal generator, which then generates LED drive pulses and other timing pulses for digital signal processing.

(2) LED driver circuit

This circuit drives an externally connected LED using the LED drive pulses generated by the timing signal generator. The duty cycle is 1/16. The S4282-51, S6986, and S10053 use a constant current drive, while the S6809, S6846, and S7136-10 use an open collector drive.

(3) Photodiode and preamp

Photocurrent generated in the photodiode is converted to a voltage via the preamp. The preamp in the S4282-51, S6986, and S10053, which are usable at high background light levels, uses an AC amplifier circuit shown in Figure 5-3 to expand the dynamic range versus DC or low-frequency fluctuating background light without impairing signal detection sensitivity.

[Figure 5-3] Preamp block diagram (S4282-51, S6986, S10053)

KPICC0025EC
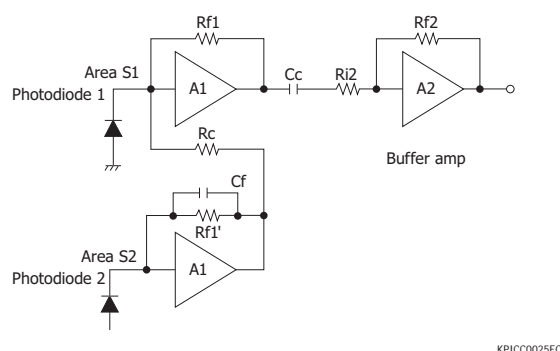
(4) Capacitive coupling, buffer amp, and reference voltage generator

Capacitive coupling removes low-frequency background light and also cancels the DC offset in the preamp simultaneously. The buffer amp amplifies the signal up to the comparator level, and the reference voltage generator generates a comparator level signal.

(5) Comparator

The comparator has a hysteresis function that prevents chattering caused by small fluctuations in the incident light.

(6) Signal processing circuit

The signal processing circuit consists of a gate circuit and a digital integration circuit. The gate circuit discriminates the comparator output to prevent possible detection errors caused by asynchronous background light. Background light that enters at the same timing as the signal detection cannot be eliminated by the gate circuit. The digital integration circuit in a subsequent stage cancels out this background light.
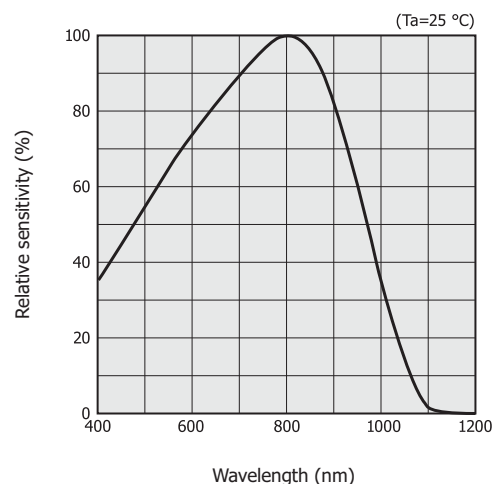
(7) Output circuit

This circuit serves as an output buffer for the signal processing circuit and outputs the signal to an external circuit.
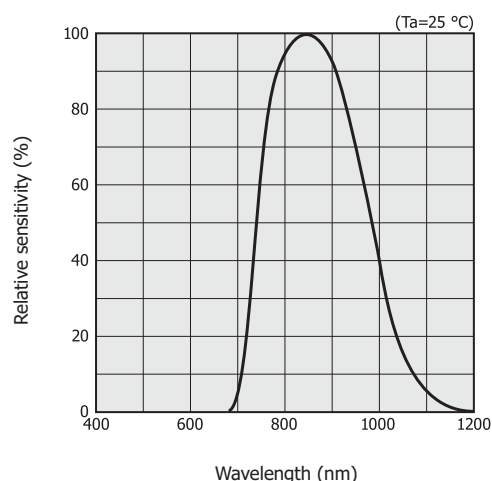
■ Characteristics

[Figure 5-4] Spectral response (typical example)
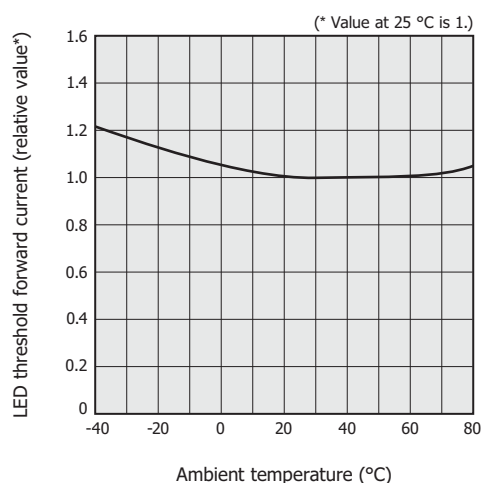
(a) S4282-51, S6986, S10053
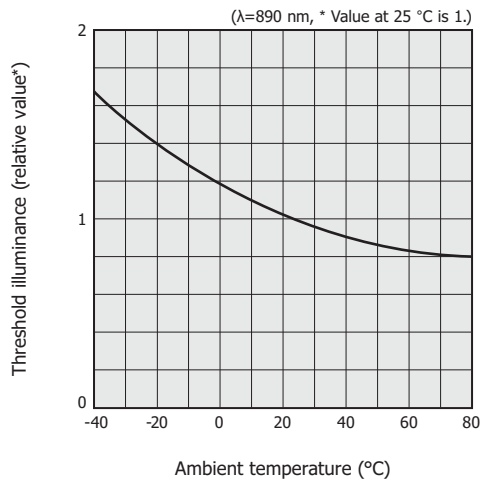
KPICB0001EB

(b) S6809, S6846, S7136-10

KPICB0002EA

[Figure 5-5] Sensitivity temperature characteristics (typical example)

(a) When used with Hamamatsu LED (λp=890 nm)

KPICB0018EB

(b) Light modulation photo IC only

(λ=890 nm, * Value at 25 °C is 1.)

Threshold illuminance (relative value*) vs Ambient temperature (°C)

KPICB0019EA

■ How to use

Optical synchronous detection type photoreflectors and photointerrupters can be easily made by connecting an infrared LED to a light modulation photo IC, which are less affected by fluctuating background light. The light modulation photo IC is used in reflection type sensors that detect an object or proximity to an object by detecting the infrared LED light reflected from the object; and also used in transmission type sensors that detect an object or a passing object by detecting whether the infrared LED light beam is interrupted by the object.

An infrared LED must be connected to the light modulation photo IC in order to perform synchronous detection. In some applications, however, connecting an LED may not be possible. In those cases, asynchronous type photo ICs are used. Asynchronous photo ICs cannot remove fluctuating background light as efficiently as the synchronous type, but they offer the advantage that they can be used without connecting to an infrared LED.

### (1) LED drive current enhancement

Detecting light over longer distances requires enhancing the LED drive current. This means that an external driver circuit must be added. Figure 5-6 shows simple external circuits using a PNP transistor to enhance the LED drive current. Another method uses a pull-up resistor connected to the LED terminal to convert LED drive pulses to logic signals before inputting the signals to the external LED driver circuit. If the photo IC and the LED drive current operate from the same power supply line, then the supply voltage may fluctuate due to the LED drive current and cause erroneous operation. If this happens, take measures to stabilize the photo IC power terminal.

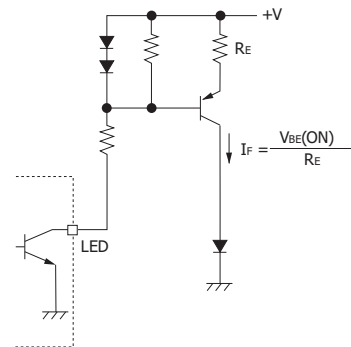### [Figure 5-6] LED drive current enhancing method

(a) All types

$$I_F = \frac{V - V_{CE}(sat) - V_F}{R}$$
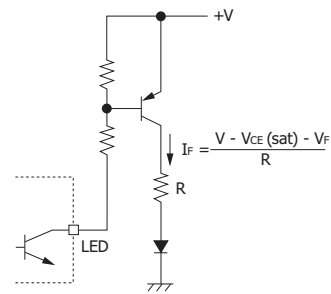
(b) S4282-51, S6986, S10053

$$I_F = \frac{V_{BE}(ON)}{R_E}$$
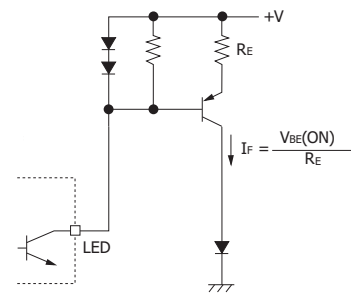
(c) S6809, S6846, S7136-10

$$I_F = \frac{V_{BE}(ON)}{R_E}$$

KPICC0028EB

(2) Sensitivity adjustment

There is no special terminal for adjusting the sensitivity of light modulation photo ICs. If sensitivity must be adjusted, then change the LED drive current. To do this, connect a variable resistor in parallel with the LED for the S4282-51, S6986, and S10053; and connect a variable resistor in series with the LED for the S6809, S6846, and S7136-10. If using an external circuit to drive the LED, adjust the external circuit constant.

[Figure 5-7] LED drive current adjusting method

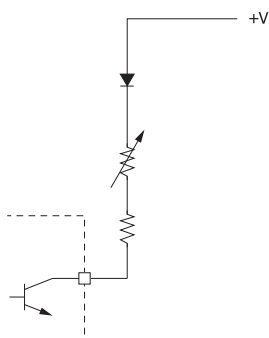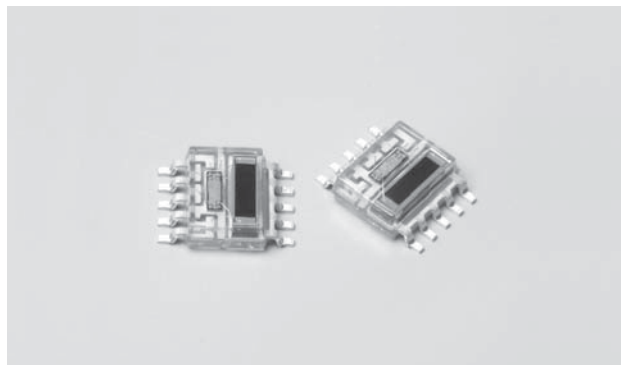(a) S4282-51, S6986, S10053

+V

(b) S6809, S6846, S7136-10

+V
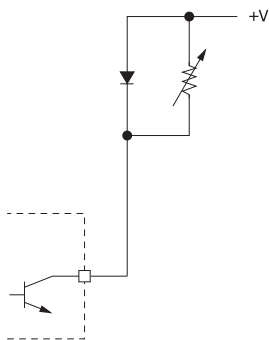
KPICC0030EB

6. Photo IC for laser beam synchronous detection

This photo IC detects the print start timing such as for laser printers. It contains a high-speed PIN photodiode and a high-speed signal processing circuit. When the laser beam passes over the photodiode, the photo IC outputs a digital signal to show the laser beam timing.

Features

- Available in high-accuracy type (dual-element photodiode) and general-purpose type (single-element photodiode)

- Compatible with a wide range of input laser power

  Internal current amplifiers are available in a 6 × type and 20 × type. The available supply voltage types are 3.3 V and 5 V. The dual-element photodiode type delivers a stable output even if the ambient temperature or input laser power fluctuates, by comparing the outputs from the two elements. The single-element photodiode type operates so that the output is inverted when the amplitude exceeds the comparator voltage set inside the IC.

- Hybrid structure

  The photo IC for laser beam synchronous detection uses a hybrid structure to make use of the features of both photodiodes and amplifiers [Figure 6-1].

[Figure 6-1] Enlarged photo
   (dual-element photodiode type S9684)
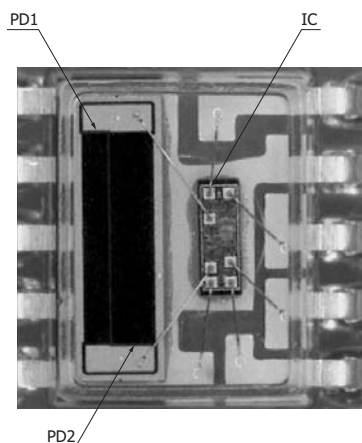
◻ Operating principle

Figure 6-2 shows a block diagram of the S9684 dual-element photodiode type. When PD1 and PD2 are irradiated with a laser beam, the respective photocurrents Ipd1 and Ipd2 flow. These photocurrents are amplified by the current amplifiers and flow as source currents Io1 and Io2 to the Ro1 and Ro2 terminals. Gain resistors R1 and R2 are externally connected between the Ro1, Ro2 terminals and GND terminal, so the voltage potential of R1 and R2 rises when the source current flows. The voltage difference between the Ro1 and Ro2 terminals is detected by a comparator and a signal then output [Figure 6-3].

If no laser beam is irradiated on PD1 and PD2, then the comparator output cannot be determined just by comparing the voltages at the Ro1 and Ro2 terminals. The comparator output must therefore be clamped at high level if no beam is irradiated on PD1 and PD2. However, just applying an offset to the circuit to set a voltage difference between the Ro1 and Ro2 terminals will cause a shift in the output timing if the input power fluctuates. To cope with this, a limit circuit made up of a bias circuit and diode D is used to clamp the lower limit of the Ro1 terminal voltage.
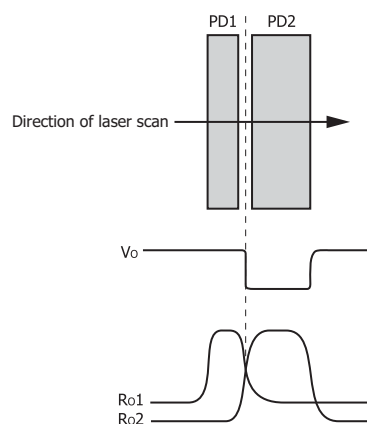
Propagation delay time variation indicates how stable output timing can be obtained with respect to fluctuations in the laser power. Dual-element photodiode types excel in this characteristic.

[Figure 6-2] Block diagram (S9684)
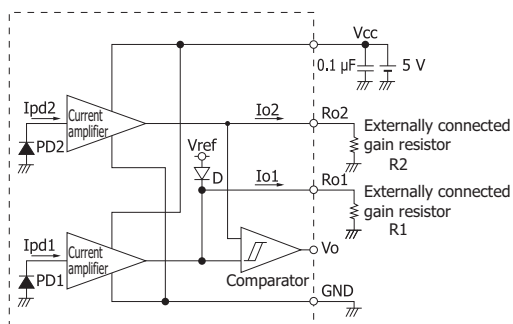
KPICC0108EB

[Figure 6-3] Terminal waveforms (S9684)

KPICC0131EB

[Figure 6-4] Propagation delay time variation vs.
          input power (S9684)
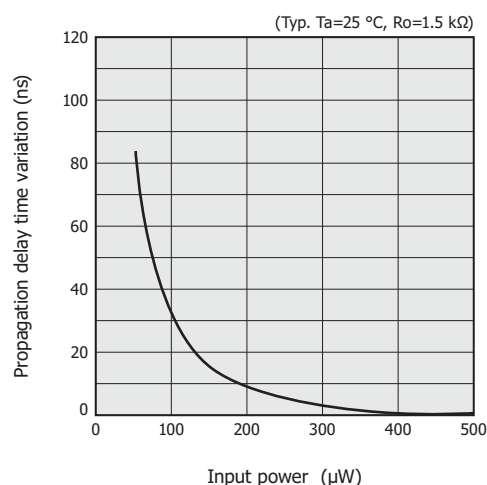
KPICB0120EB

◻ How to use

Connect an external gain resistor (10 kΩ max.) between Ro1 and GND (or Vcc on some products) and also between Ro2 and GND (or Vcc on some products) [Figure 6-2]. When a laser beam is scanned over PD1 and PD2, analog waveforms such as shown in Figure 6-5 are observed at the Ro1 and Ro2 terminals.

The beam is scanned from PD1 toward PD2. This allows the steep falling edge to be used as a timing signal for output.

To ensure that the output timing is stable, the input laser power and the gain resistance must be set so that the analog waveform amplitudes of Ro1 and Ro2 are 2 to 3 V.

[Figure 6-5] Waveform example (S9684)

Vo
Vertical axis:
5 V/div.

GND

Ro1
Ro2
Vertical axis:
1 V/div.

GND
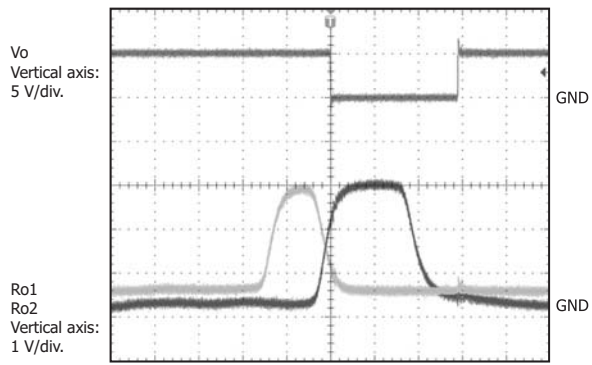
Hamamatsu Photo ICs are widely used for many different applications.

| Clock: light/dark sensing | Photo IC diode, Schmitt trigger circuit photo IC |

| Station ticket gate: passenger sensing | Light modulation photo IC |

| Air conditioner: light/dark sensing | Photo IC diode |

| Vending machine: light/dark sensing | Photo IC diode |
| Vending machine: coin detection | Light modulation photo IC |

| Auto lighting equipment: light/dark sensing | Photo IC diode |

| TV: light/dark and color sensing | Photo IC diode, digital color sensor |

| Auto hand washer: hand sensing | Light modulation photo IC |

| Boiler: flame eye | Photo IC diode |
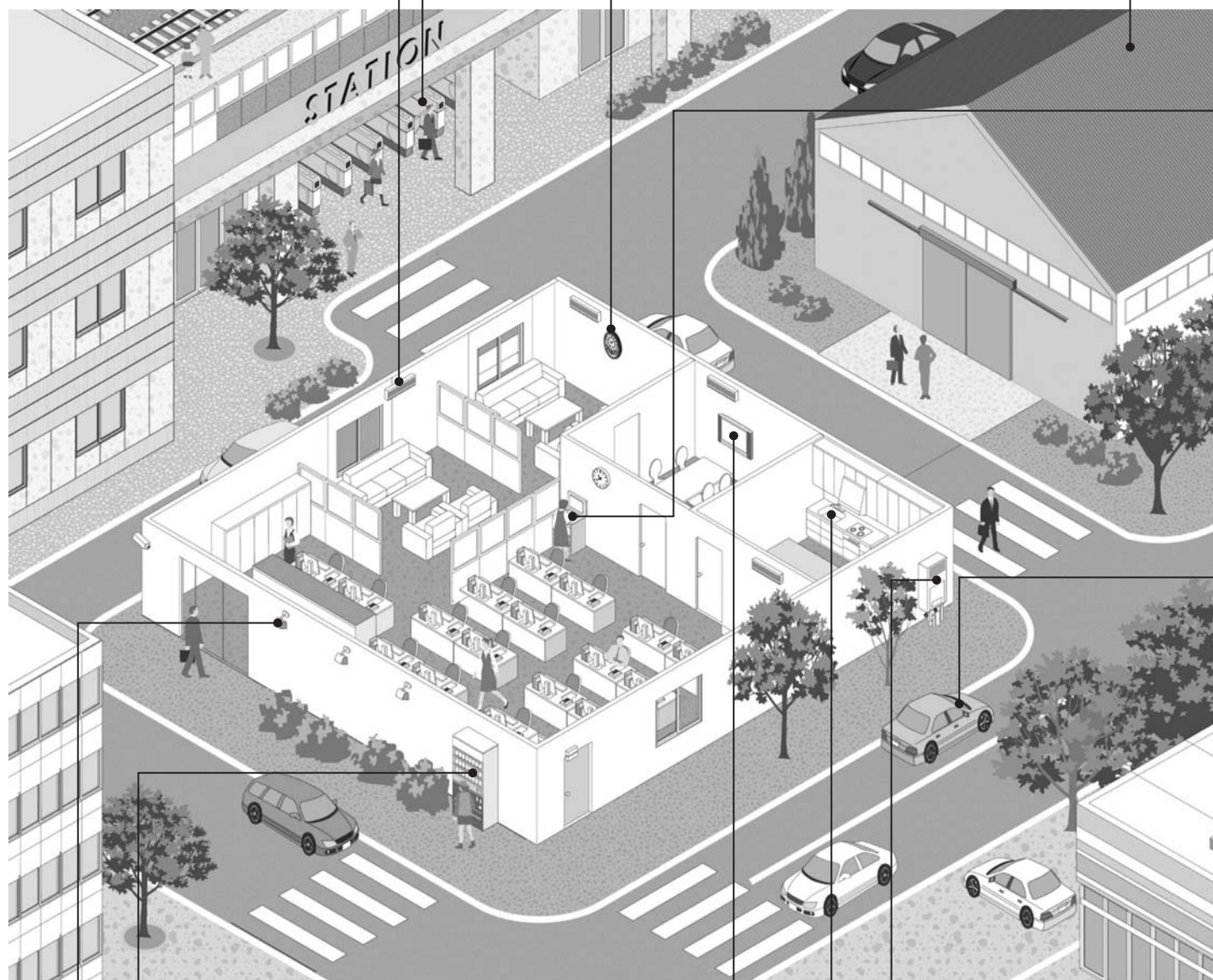
Factories

Safety devices
Light modulation photo IC
Photo IC for optical switch

Signal transmission
Transmitter/receiver photo IC for optical link

Detection of product passage
Light modulation photo IC
Photo IC for optical switch

Digital copiers, multifunctional digital office machines

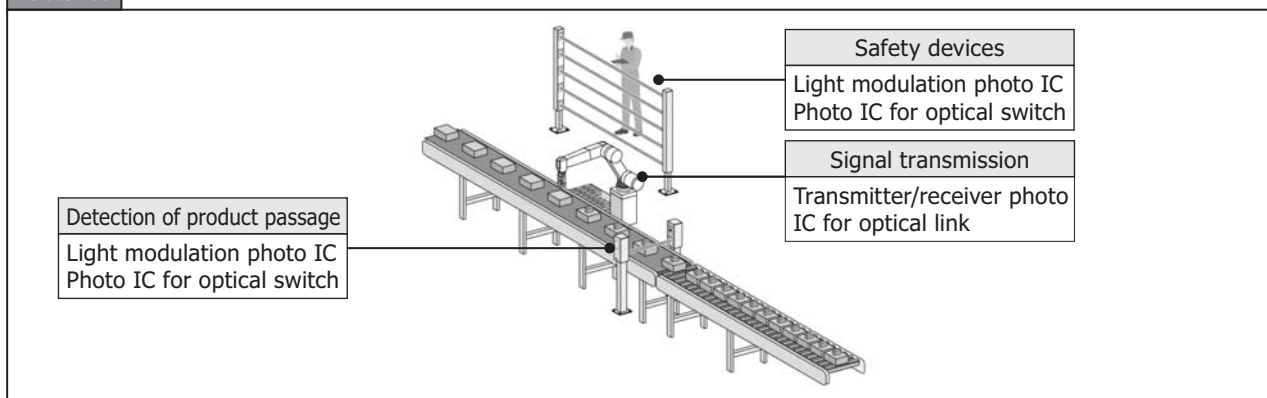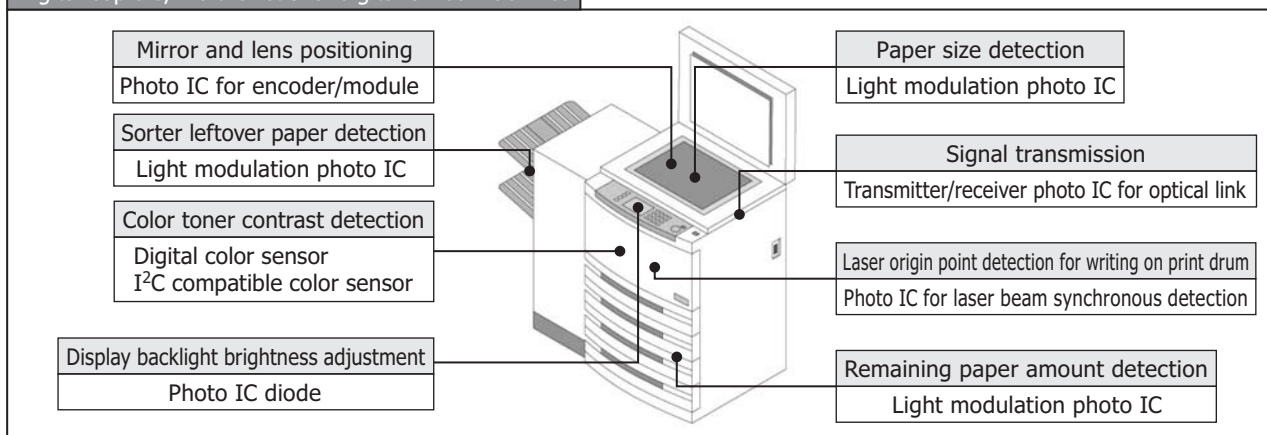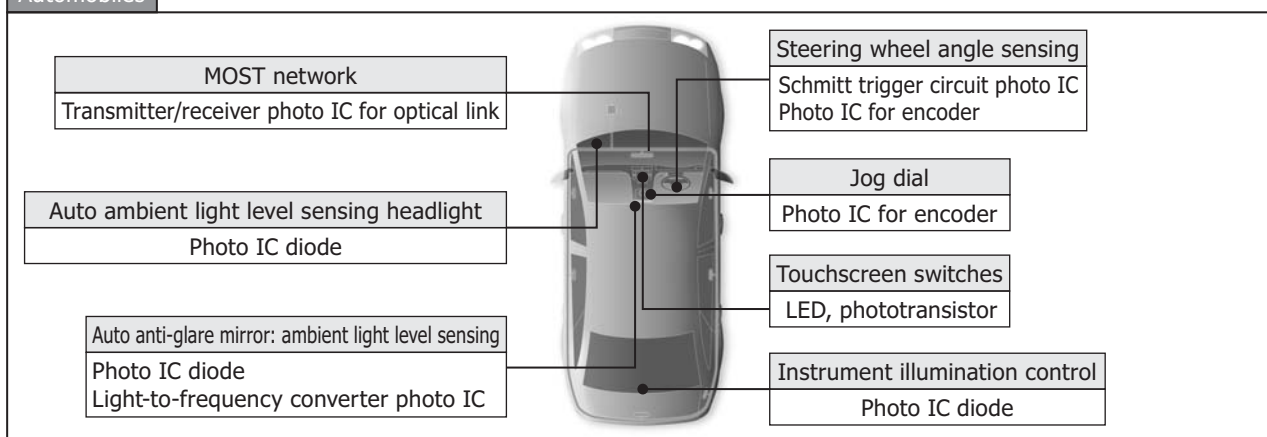**Mirror and lens positioning**
Photo IC for encoder/module

Sorter leftover paper detection
Light modulation photo IC

Color toner contrast detection
Digital color sensor
I^2C compatible color sensor

Display backlight brightness adjustment
Photo IC diode

Paper size detection
Light modulation photo IC

Signal transmission
Transmitter/receiver photo IC for optical link

Laser origin point detection for writing on print drum
Photo IC for laser beam synchronous detection

Remaining paper amount detection
Light modulation photo IC

Automobiles

MOST network
Transmitter/receiver photo IC for optical link

Auto ambient light level sensing headlight
Photo IC diode

Auto anti-glare mirror: ambient light level sensing
Photo IC diode
Light-to-frequency converter photo IC

Steering wheel angle sensing
Schmitt trigger circuit photo IC
Photo IC for encoder

Jog dial
Photo IC for encoder

Touchscreen switches
LED, phototransistor

Instrument illumination control
Photo IC diode

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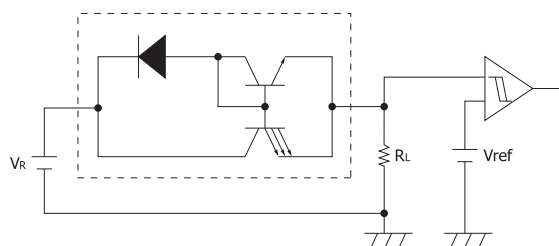## 7 - 1 Simple illuminometers

■ Application example of photo IC diode

Here we show a simple illuminometer made from a photo IC diode and a comparator. A simple illuminometer can be made by utilizing the features of photo IC diodes (good linearity and small variations in output current). This meter can be turned on at a specified illuminance level as shown in the connection example in Figure 7-1 by inputting the voltage generated across load resistor R_L into the comparison terminals on the comparator (LM111 and the like).

Photo IC diodes with spectral response characteristics near human eye sensitivity are used in the following applications.

· Energy-saving sensors on TV and other appliances
· Backlight adjustment on cell phones
· Brightness adjustment on LCD panels
· Ambient light level sensing on vehicle anti-glare mirrors
· Auto light sensors

[Figure 7-1] Connection example (photo IC diode)

Note: Drawing surrounded by dotted lines shows a schematic diagram of photo IC diode.

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### ■ Application example of light-to-frequency converter photo IC

This is a simple illuminometer made from a light-to-frequency converter photo IC and a single-chip microcontroller PIC12F675 (made by Microchip Technology Inc.). The internal 16-bit timer of PIC12F675 is used. The light-to-frequency converter photo IC and microcontroller are connected to the same power supply, and the photo IC output is connected to the timer input pin (no. 2) on the microcontroller. The illuminance level appears on the LEDs. Figure 7-3 shows a program example. The output appears in binary, and when the number increases by 1, then the brightness doubles. The logarithmic display is close to that of human eye sensitivity.

[Figure 7-2] Connection example
(light-to-frequency converter photo IC)
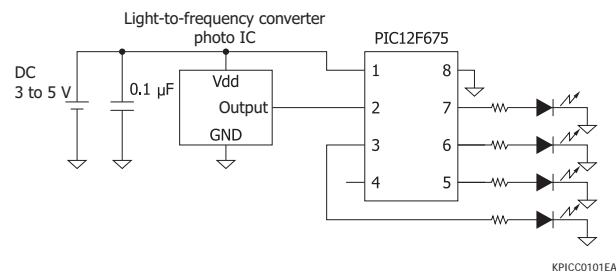

KPICC0101EA

[Figure 7-3] Program example
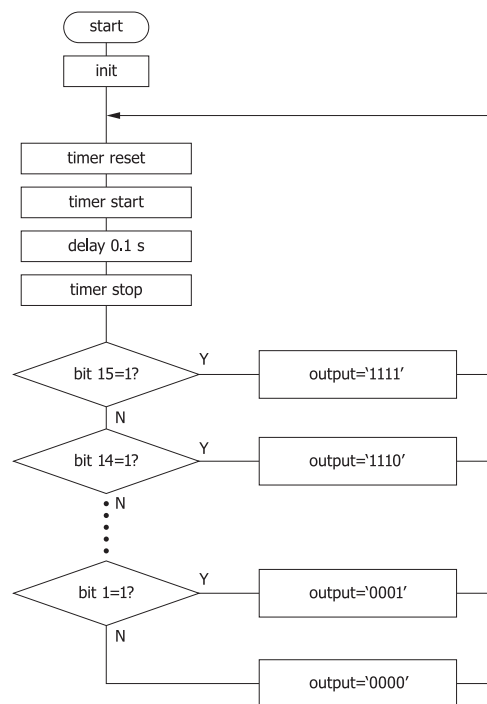
KPICC0102EA

7 - 2 High-speed digital transmission
(application example of photo IC for optical link)

High-speed digital transmission has become an essential part of digital media and equipment in recent years. Metal cables have the problem that they require some means to reduce external noise to ensure high transmission quality. In contrast, plastic optical fibers (POF) are unaffected by the noise and so are suitable for use in extremely noisy environments. Hamamatsu offers a wide lineup of photo ICs for optical link ranging from those for digital audio equipment up to 6.25 Gbps. These photo ICs are utilizable in consumer electronics, FA (factory automation), OA (office automation) equipment, in-vehicle networks, and home networks, etc.

[Figure 7-4] In-vehicle network (MOST)
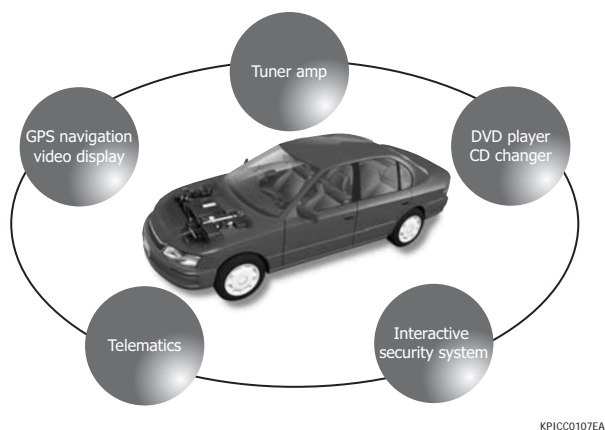
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7 - 3　LED backlight LCD display color adjustment (application example of digital color sensor)

The backlight brightness on LCD displays using RGB-LED backlighting is usually regulated by a microcontroller. Since the backlight deteriorates over time, the color sensor is used to monitor the backlight level. The brightness information is fed back to the microcontroller, which then adjusts the backlight brightness to maintain a stable display. Digital color sensors provide digital input/output signals that can be directly connected to the microcontroller.

[Figure 7-5] Connection example (digital color sensor)
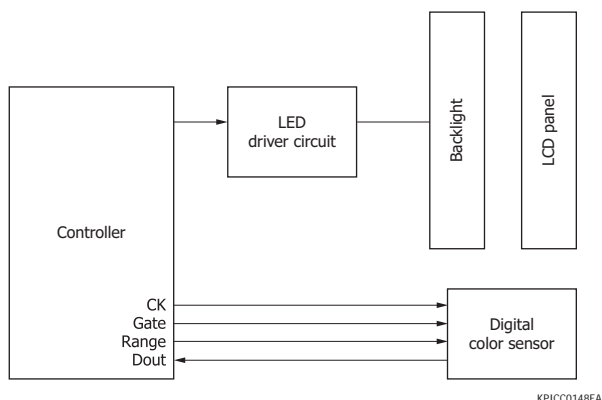
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7 - 4　Multifunctional sensor for smartphones (application example of color/proximity sensor)

Smartphones contain sensors for adjusting the image quality of the LCD display and for turning on and off the touchscreen and LEDs for indicating incoming calls. Since the amount of space inside a smartphone is limited, mounted components need to be small. Hamamatsu color/proximity sensor integrates such functions in a single small package to reduce the amount of space used by components. This sensor operates on low voltage (2.5 V or 3.3 V) and also have a standby mode, minimizing its power consumption.

The color/proximity sensor was designed for smartphones, but it can also be used in a wide range of applications that require object sensing and brightness and color adjustment.

[Figure 7-6] Color/proximity sensor used in smartphones
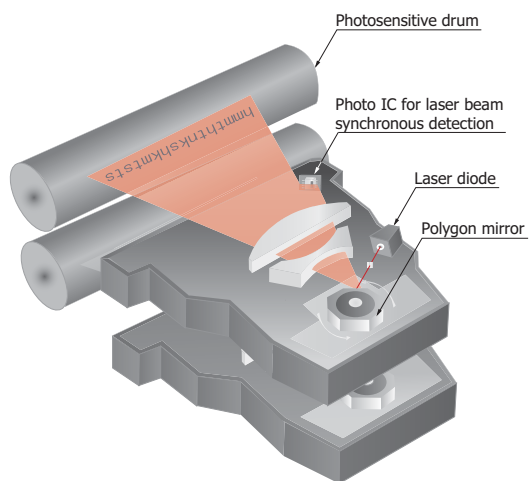

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7 - 5　Print start timing signal output for digital copiers and laser printers (application example of photo IC for laser beam synchronous detection)

Digital copiers and laser printers record an electrostatic latent image on a photosensitive medium by scanning with an intensity-modulated laser beam. In this type of raster scanning, it is essential to synchronize the scanning signal. To do this, a photosensor is mounted at the position where the main scanning starts, in order to generate a synchronization signal by utilizing the received light signal from the photosensor.

The photo IC for laser beam synchronous detection outputs a print start timing signal. A timing signal is then generated when the laser beam passes the position where this photo IC is mounted and the signal sent to the phase control circuit. The phase control circuit then uses this timing signal to set the timing for writing the raster information from the laser intensity modulator circuit.

Hamamatsu offers two types of photo ICs for laser beam synchronous detection. One is a high-precision type (dual-element photodiode) and the other is a general-purpose type (single-element photodiode).

[Figure 7-7] Schematic of laser printer

Photosensitive drum

Photo IC for laser beam synchronous detection

Laser diode

Polygon mirror

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